

# MF3ICD8101

MIFARE DESFire contactless multi-application IC  
BL-ID Doc. No.: 145610

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Objective short data sheet

## 1. General description

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NXP has developed the MIFARE DESFire (MF3ICD8101) to be used with Proximity Coupling Devices (PCDs) according to ISO/IEC 14443 Type A. The transport protocol complies to part ISO/IEC 14443-4. The MF3ICD8101 is primarily designed for secure contactless transport applications and related loyalty programs.

## 2. Features

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### 2.1 RF Interface: ISO/IEC 14443 Type A

- Contactless transmission of data and powered by the RF-field (no battery needed)
- Operating distance: Up to 100 mm (depending on antenna geometry)
- Operating frequency: 13.56 MHz
- Fast data transfer: 106 kbit, 212 kbit, 424 kbit, 848 kbit
- High data integrity: 16-bit/32-bit CRC, parity, bit coding, bit counting; CMAC; MAC
- True deterministic anticollision
- 7 byte unique identifier (cascade level two according to ISO/IEC 14443-3)
- Uses ISO/IEC 14443-4 protocol

### 2.2 ISO/IEC 7816 compatibility (only software version 0.6 and higher)

- Supports ISO/IEC 7816-3 APDU message Structure
- Supports ISO/IEC 7816-4 INS code 'A4' SELECT
- Supports ISO/IEC 7816-4 INS code 'B0' READ BINARY
- Supports ISO/IEC 7816-4 INS code 'D6' UPDATE BINARY
- Supports ISO/IEC 7816-4 INS code 'B2' for READ RECORDS
- Supports ISO/IEC 7816-4 INS code 'E2' for APPEND RECORD
- Supports ISO/IEC 7816-4 INS code '84' for GET CHALLENGE
- Supports ISO/IEC 7816-4 INS code '88' for INTERNAL AUTHENTICATE
- Supports ISO/IEC 7816-4 INS code '82' for EXTERNAL AUTHENTICATE

### 2.3 Non-volatile memory

- 8 kB NV-Memory
- Data retention of 10 years
- Write endurance typical 500 000 cycles

## 2.4 NV-memory organization

- Flexible file system
- Up to 28 applications simultaneously on one PICC
- Up to 32 files in each application

## 2.5 Security

- Unique 7 byte serial number for each device
- Mutual three pass authentication
- Mutual authentication according to ISO/IEC 7816-4
- Data encryption on RF-channel with replay attack protection:
- Hardware DES using 56-bit, 112-bit and 168-bit keys featuring key version, data authenticity by 8 byte CMAC
- Hardware AES using 128-bit keys featuring key version, data authenticity by 8 byte CMAC
- Authentication on application level
- Hardware exception sensors
- Self-securing file system
- Backward compatibility to MF3ICD4001: 4 byte MAC

## 3. Applications

- Transport
- Access control
- Loyalty
- Internet applications

## 4. Quick reference data

Table 1. Quick reference data [1][2]

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
C <sub>ISS</sub>	input capacitance (LCR meter HP4258)	22 °C, 13.56 MHz, 2 V	14.96	17.0	19.04	pF
t <sub>W</sub>	EEPROM write time		-	2.9	-	ms
t <sub>RET</sub>	EEPROM data retention		10	-	-	years
N <sub>WE</sub>	EEPROM write endurance		200000	500000	-	cycles
f <sub>i</sub>	input frequency		-	13.56	-	MHz

[1] Stresses above one or more of the values may cause permanent damage to the device

[2] Exposure to limiting values for extended periods may affect device reliability

## 5. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
MF3ICD8101DUD/01	Wafer	Die on sawn wafer	-

## 6. Block diagram

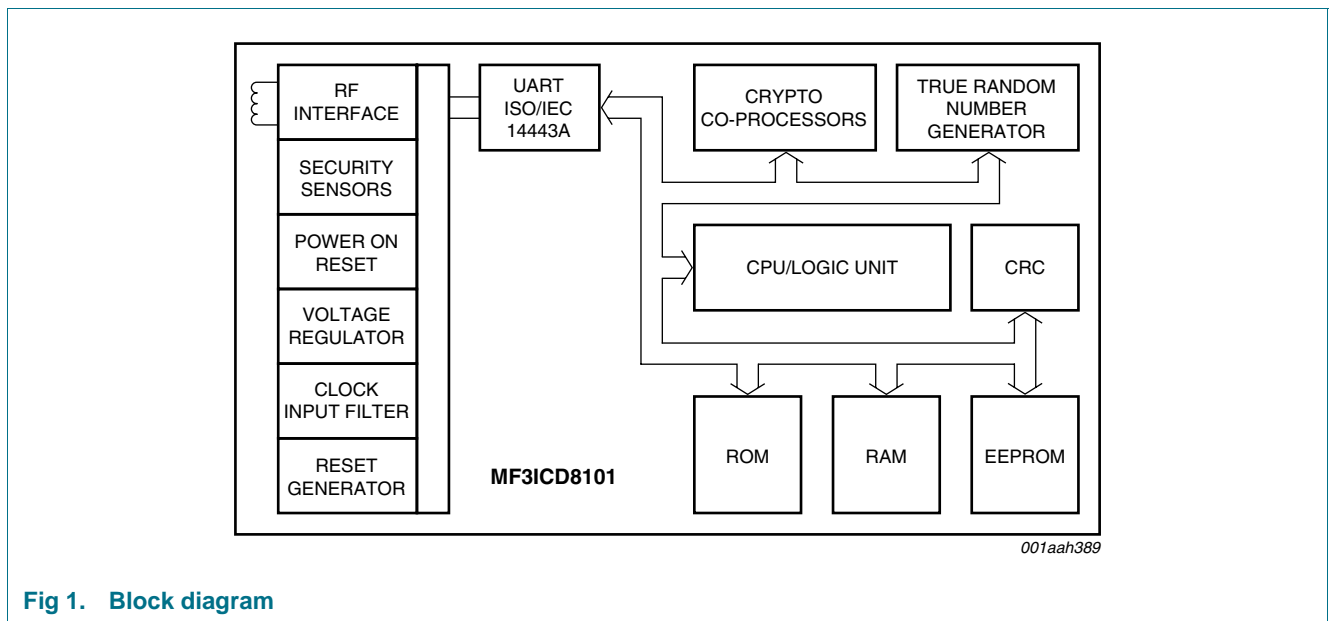


Fig 1. Block diagram

## 7. Limiting values

Table 3. Limiting values [1][2]

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$I_I$	input current		-	30	mA
$P_{tot (pack)}$	total power dissipation per package		-	200	mW
$T_{stg}$	storage temperature		-55	125	°C
$T_{oper}$	operating temperature		-25	70	°C
$V_{esd}$	electrostatic discharge voltage	[3]	2	-	kV
$I_{lu}$	latch-up current		± 100	-	mA

[1] Stresses above one or more of the limiting values may cause permanent damage to the device

[2] Exposure to limiting values for extended periods may affect device reliability

[3] MIL Standard 883-C method 3015; Human body model: C = 100 pF, R = 1.5 kΩ

## 8. Functional description

### 8.1 Contactless energy and data transfer

In the MIFARE system, the MF3ICD8101 is connected to a coil consisting of a few turns embedded in a standard ISO/IEC smart card. No battery is needed. When the card is positioned in the proximity of the PCD antenna, the high speed RF communication interface allows to transmit data with up to 848 kbit/s.

### 8.2 Anticollision

An intelligent anticollision mechanism allows handling more than one PICC in the field simultaneously. The anticollision algorithm selects each PICC individually and ensures that the execution of a transaction with a selected PICC is performed correctly without data corruption resulting from other PICCs in the field.

### 8.3 UID/serial number

The unique 7 byte serial number (UID) is programmed into a locked part of the NV-memory which is reserved for the manufacturer. Due to security and system requirements these bytes are write-protected after being programmed by the IC manufacturer at production time. According to ISO/IEC 14443-3 during the first anticollision loop the cascade tag will be returned 0x88 and the first 3 bytes of the UID, SN0 to SN2 and BCC. The second anticollision loop will return bytes SN3 to SN6 and BCC.

SN0 holds the Manufacturer ID for NXP (04h) according to ISO/IEC 14443-3 and ISO/IEC 7816-6 AMD 1.

### 8.4 Memory organization

The 8 kB NV-memory is organized using a flexible file system. This file system allows a maximum of 28 different applications on one single PICC. Each application provides up to 32 files. Every application is represented by its 3 bytes Application IDentifier, AID.

Five different file types are supported.

A guideline to assign DESFire AIDs can be found in the application note "MIFARE Application Directory, MAD".

Each file can be created either at PICC initialization (card production / card printing), at PICC personalization (vending machine) or in the field.

If a file or application becomes obsolete in operation, it can be permanently invalidated.

Commands which have impact on the file structure itself (e.g. creation or deletion of applications, change of keys) activate an automatic rollback mechanism, which protects the file structure from getting corrupted.

If this rollback is necessary, it is done without user interaction before carrying out further commands. To ensure data integrity on application level, a transaction oriented backup is implemented for all file types with backup. It is possible to mix file types with and without backup within one application.

## 8.5 Available file types

The files within an application can be of different types as:

- Standard Data Files
- Backup Data Files
- Value Files with Backup
- Linear Record Files with Backup
- Cyclic Record Files with Backup

## 8.6 Security

The 7 byte UID is unchangeably programmed into each device during production. It cannot be altered and ensures the uniqueness of each device.

The UID may be used to derive diversified keys for each ticket. Diversified PICC keys contribute to gain an effective anti-cloning mechanism.

**Remark:** For new authentications other than 0Ah, the init vector for the calculation of the MAC is only reset to '00h' after the authentication. So the init vector shall be remembered during the whole transaction until a new authentication is calculated.

## 8.7 3 pass authentication

Prior to data transmission a mutual three pass authentication can be done between PICC and PCD depending on the configuration employing either 56-bit DES (single DES, DES), 112-bit DES (triple DES, 3DES), 168-bit DES (3 key triple DES, 3K3DES) or AES. During the authentication the security level of all further commands during the session is set.

Three pass authentication proves that both parties (PCD and PICC) are owner of a common secret (DES, 3DES, 3K3DES, AES key). The result of a successful authentication is a trusted link between both parties. The authentication command also yields a session key that you can use to protect the data transmission channel.

## 9. DESFire command set

### 9.1 ISO/IEC 14443-3:

Table 4. ISO/IEC 14443-3

Command	Description
REQA	REQA and ATQA are implemented fully according to ISO/IEC 14443-3.
WUPA	WAKE-UP is implemented fully according to ISO/IEC 14443-3.
ANTICOLLISION / SELECT Cascade Level 1	The ANTICOLLISION and SELECT commands are implemented fully according to ISO/IEC 14443-3. The response is part 1 of the UID.
ANTICOLLISION / SELECT Cascade Level 2	The ANTICOLLISION and SELECT commands are implemented fully according to ISO/IEC 14443-3. The response is part 2 of the UID.

### 9.2 ISO/IEC 14443-4:

Table 5. ISO/IEC 14443-4:

Command	Description
RATS	The response to the RATS command identifies the PICC type to the PCD.
PPS	The PPS command allows an individual selection of the communication baud rate between PCD and PICC. For DESFire it is possible to individually set the communication baud rate independently for both directions i.e. DESFire allows a non-symmetrical information interchange speed.
WTX	If the PICC needs more time than the defined FWT to respond to a PCD command it will send a request for a waiting time extension.

### 9.3 MF3ICD8101 command set overview – security related commands:

Table 6. Security related commands

Command	Description
Authenticate	In this procedure both, the PICC as well as the reader device, show in an encrypted way that they possess the same secret which especially means the same key. This procedure not only confirms that both entities are permitted to do operations on each other but also creates a session key which can be used to keep the further communication path secure. As the name "session key" implicitly indicates, each time a new authentication procedure is successfully completed a new key for further cryptographic operations is generated.
Change KeySettings	Changes the master key settings on PICC and application level.
Set Configuration	Configures the card and pre personalizes the card with a key, defines if the UID or the random ID is sent back during communication setup and configures the ATS string.
Change Key	Changes any key stored on the PICC.
Get KeyVersion	Reads out the current key version of any key stored on the PICC.

**Remark:** All command & data frames are exchanged between PICC and PCD by using block format as defined in ISO/IEC 14443-4.

## 9.4 MF3ICD8101 command set overview – PICC level commands:

Table 7. PICC level commands

Command	Description
Create Application	Creates new applications on the PICC.
Delete Application	Permanently deactivates applications on the PICC.
Get Applications IDs	Returns the Application IDentifiers of all applications on a PICC.
Free Memory	Returns the free memory available on the card
GetDFNames	Returns the DF names
Get KeySettings	Gets information on the PICC and application master key settings. In addition it returns the maximum number of keys which are configured for the selected application.
Select Application	Selects one specific application for further access.
FormatPICC	Releases the PICC user memory.
Get Version	Returns manufacturing related data of the PICC.
GetCardUID	Returns the UID.

**Remark:** All command & data frames are exchanged between PICC and PCD by using block format as defined in ISO/IEC 14443-4.

## 9.5 MF3ICD8101 command set overview – application level commands:

Table 8. Application level commands

Command	Description
Get FileIDs	Returns the File IDentifiers of all active files within the currently selected application.
Get FileSettings	Get information on the properties of a specific file.
Change FileSettings	Changes the access parameters of an existing file.
Create StdDataFile	Creates files for the storage of plain unformatted user data within an existing application on the PICC.
Create BackupDataFile	Creates files for the storage of plain unformatted user data within an existing application on the PICC, additionally supporting the feature of an integrated backup mechanism.
Create ValueFile	Creates files for the storage and manipulation of 32-bit signed integer values within an existing application on the PICC.
Create LinearRecordFile	Creates files for multiple storage of structural similar data, for example for loyalty programs, within an existing application on the PICC. Once the file is filled completely with data records, further writing to the file is not possible unless it is cleared.
Create CyclicRecordFile	Creates files for multiple storage of structural similar data, for example for logging transactions, within an existing application on the PICC. Once the file is filled completely with data records, the PICC automatically overwrites the oldest record with the latest written one. This wrap is fully transparent for the PCD.
DeleteFile	Permanently deactivates a file within the file directory of the currently selected application.

**Remark:** All command & data frames are exchanged between PICC and PCD by using block format as defined in ISO/IEC 14443-4.

## 9.6 MF3ICD8101 command set overview – data manipulation commands:

**Table 9. Data manipulation commands**

Command	Description
Read Data	Reads data from Standard Data Files or Backup Data Files.
Write Data	Writes data to Standard Data Files or Backup Data Files.
Get Value	Reads the currently stored value from Value Files.
Credit	Increases a value stored in a Value File.
Debit	Decreases a value stored in a Value File.
Limited Credit	Allows a limited increase of a value stored in a Value File without having full Credit permissions to the file.
Write Record	Writes data to a record in a Cyclic or Linear Record File.
Read Records	Reads out a set of complete records from a Cyclic or Linear Record File.
Clear RecordFile	Resets a Cyclic or Linear Record File to empty state.
Commit Transaction	Validates all previous write access' on Backup Data Files, Value Files and Record Files within one application.
Abort Transaction	Invalidates all previous write access' on Backup Data Files, Value Files and Record Files within one application.

**Remark:** All command & data frames are exchanged between PICC and PCD by using block format as defined in ISO/IEC 14443-4.

## 9.7 MF3ICD8101 command set- ISO/IEC 7816 APDU commands:

The MF3ICD8101 provides the following command set according to ISO/IEC 7816-4 clause 6:

- INS code 'A4' SELECT
- INS code 'B0' READ BINARY
- INS code 'D6' UPDATE BINARY
- INS code 'B2' READ RECORDS
- INS code 'E2' APPEND RECORD
- INS code '84' GET CHALLENGE
- INS code '88' INTERNAL AUTHENTICATE
- INS code '82' EXTERNAL AUTHENTICATE

### 9.7.1 ISO/IEC 7816-4 APDU message structure:

DESFire supports the APDU message structure according to ISO/IEC 7816-4 for

- an optional wrapping of the native DESFire APDU format
- for the additionally implemented ISO/IEC 7816-4 commands



## 10. Abbreviations

**Table 10. Abbreviations**

Acronym	Description
AES	Advanced Encryption Standard
AID	Application Identifier
APDU	Application Protocol Data Unit
ATS	Answer to Select
CMAC	Cryptic Message Authentication Code
CRC	Cyclic Redundancy Check
DES	Digital Encryption Standard
DF	Dedicated File
EEPROM	Electrically Erasable Programmable Read-Only Memory
FWT	Frame Waiting Time
INS	Instructions
MAC	Message Authentication Code
MAD	MIFARE Application Directory
NV	Non Volatile Memory
PCD	Proximity Coupling Device
PICC	Proximity Integrated Circuit Card
PPS	Protocol Parameter Selection
RATS	Request Answer To Select
REQA	Request Answer
RF	Radio Frequency
UID	Unique Identifier
WTX	Waiting Time Extension
WUPA	Wake Up Protocol A

## 11. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
MF3ICD8101_SDS_N_1	20071211	Objective short data sheet	-	-
	<ul style="list-style-type: none"><li>Initial version</li></ul>			

## 12. Legal information

### 12.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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